

DDR4 DIMM

TE Internal #: 2309410-1

Small Outline (SO), 5.2 mm [.205 in] Stack Height, Right Angle  
Module Orientation, 200 / 260 Position, DDR4 DIMM, SO DIMM  
Sockets

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR4 SO DIMM Sockets



DRAM Type: **Small Outline (SO)**  
Stack Height: **5.2 mm [ .205 in ]**  
Module Orientation: **Right Angle**  
Number of Positions: **200, 260**  
Centerline (Pitch): **.5 mm, 3.3 mm [ .02 in, .129 in ]**

[All DDR4 SO DIMM Sockets \(39\)](#)

Features

Product Type Features

|                                   |                       |
|-----------------------------------|-----------------------|
| Connector & Contact Terminates To | Printed Circuit Board |
| Connector System                  | Cable-to-Board        |
| DRAM Type                         | Small Outline (SO)    |

Configuration Features

|                     |             |
|---------------------|-------------|
| Number of Keys      | 1           |
| Number of Rows      | 2           |
| Module Orientation  | Right Angle |
| Number of Positions | 200, 260    |

Electrical Characteristics

|              |       |
|--------------|-------|
| DRAM Voltage | 1.2 V |
|--------------|-------|

Signal Characteristics

|               |       |
|---------------|-------|
| SGRAM Voltage | 1.2 V |
|---------------|-------|

Body Features

|                         |              |
|-------------------------|--------------|
| Retention Post Location | Both Ends    |
| Retention Post Material | Copper Alloy |
|                         |              |



|                   |                                |
|-------------------|--------------------------------|
| Latch Material    | High Temperature Thermoplastic |
| Ejector Type      | Locking                        |
| Ejector Location  | Both Ends                      |
| Connector Profile | Low                            |

Contact Features

|                                               |              |
|-----------------------------------------------|--------------|
| Contact Current Rating (Max)                  | .5 A         |
| Contact Underplating Material                 | Nickel       |
| Memory Socket Type                            | Memory Card  |
| Contact Base Material                         | Copper Alloy |
| PCB Contact Termination Area Plating Material | Gold Flash   |
| Contact Mating Area Plating Material          | Gold Flash   |

Termination Features

|                           |               |
|---------------------------|---------------|
| Insertion Style           | Cam-In        |
| Termination Method to PCB | Surface Mount |

Mechanical Attachment

|                          |                |
|--------------------------|----------------|
| Connector Mounting Type  | Board Mount    |
| PCB Mount Retention Type | Solder Peg     |
| Mating Alignment Type    | Reverse Keying |
| PCB Mount Retention      | With           |

Housing Features

|                    |                                |
|--------------------|--------------------------------|
| Housing Material   | High Temperature Thermoplastic |
| Housing Color      | Black                          |
| Centerline (Pitch) | .5 mm, 3.3 mm[.02 in][.129 in] |

Dimensions

|                    |                 |
|--------------------|-----------------|
| Stack Height       | 5.2 mm[.205 in] |
| Row-to-Row Spacing | 8.2 mm[.322 in] |

Usage Conditions

|                             |                           |
|-----------------------------|---------------------------|
| Operating Temperature Range | -55 – 85 °C[-67 – 185 °F] |
|-----------------------------|---------------------------|

Operation/Application

|                     |       |
|---------------------|-------|
| Circuit Application | Power |
|---------------------|-------|

Industry Standards

|                        |          |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|



Packaging Features

|                    |             |
|--------------------|-------------|
| Packaging Quantity | 800         |
| Packaging Method   | Tape & Reel |

Product Compliance

For compliance documentation, visit the product page on TE.com>

|                                               |                                                                                                                               |
|-----------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------|
| EU RoHS Directive 2011/65/EU                  | Compliant                                                                                                                     |
| EU ELV Directive 2000/53/EC                   | Compliant                                                                                                                     |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold                                                                                       |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JAN 2025 (247)<br>Candidate List Declared Against: JAN 2025 (247)<br>Does not contain REACH SVHC |
| Halogen Content                               | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free                                           |
| Solder Process Capability                     | Reflow solder capable to 260°C                                                                                                |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts







Also in the Series

DDR4 DIMM

DIMM Sockets(25)

SO DIMM Sockets(39)

Customers Also Bought

TE Part #2000895-2  
Fortis Zd 10 Col vert end mod assy

TE Part #2309407-1  
DDR4 SODIMM 260P 4.0H STD

TE Part #ZPF000000000100858  
DMC-MD 24 D

TE Part #1-338086-6  
6/6 INV.MOD.JACK

TE Part #1622725-1  
LR2 1% 2K2

TE Part #5-1614882-0  
CPF 0603 15K 0.1% 25PPM 5K RL

TE Part #2102315-2  
Fortis Zd 10 Col R/A Center Assy SE

TE Part #1-2176337-1  
CRGCO 0402 68R 1%

TE Part #5069802018  
CGPT-1.6/0.8-0-STK

TE Part #2828646-1  
ASSY SKT MODULE, 16-02 PCB STRAIGHT, LOW

Documents

Product Drawings

DDR4 SODIMM 260P 5.2H RVS

English

CAD Files

3D PDF

3D



Customer View Model

[ENG\\_CVM\\_CVM\\_2309410-1\\_1.2d\\_dxf.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_2309410-1\\_1.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_2309410-1\\_1.3d\\_stp.zip](#)

English

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Product Specifications

[Application Specification](#)

English